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WHAT IS CLAIMED IS:

1. A packaging structure integrating passive devices, comprising:

a leadframe, wherein the leadframe includes a plurality of first leads defining a chip-bonding region, a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region, and a die pad located in the chip-bonding region;

a chip bonded onto the die pad;

at least a passive device mounted between and connected to the contact pads;

a plurality of bonding wires electrically connecting the chip, the passive device, and the first and second leads to one another; and

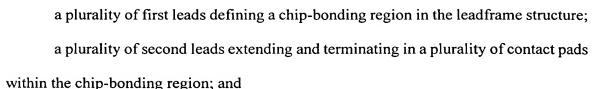
an encapsulant material encapsulating the chip, the passive device, and the bonding wires.

- 2. The packaging structure of claim 1, wherein the passive device connects the contact pads by surface mount technology.
- 3. The packaging structure of claim 1, wherein a portion of each first and second lead extends out of the encapsulant material.
 - 4. A quad flat package including the packaging structure of claim 1.
 - 5. A plastic chip carrier package including the packaging structure of claim 1.
- 6. The packaging structure of claim 1, further including an adhesive tape disposed on bottom surfaces of the contact pads to improve a rigidity of the contact pads.
- 7. The packaging structure of claim 1, wherein the passive device is a resistor, a capacitor or an inductor.
- 8. A leadframe structure suitable for use in a chip packaging structure, the leadframe structure comprising:

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- a die pad arranged in the chip-bonding region.
- 9. The leadframe structure of claim 8, further including an adhesive tape bonded to bottom surfaces of the contact pads to improve a rigidity of the contact pads.
 - 10. A packaging structure integrating passive devices, comprising:
- a leadframe, wherein the leadframe includes a plurality of first leads defining a chip-bonding region, a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region, and a die pad located in the chip-bonding region;

an adhesive tape bonded to bottom surfaces of the contact pads;

a chip bonded onto the die pad;

at least a passive device mounted between and connected to the contact pads;

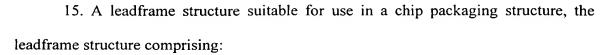
a plurality of bonding wires electrically connecting the chip, the passive device, and the leads to one another; and

an encapsulant material encapsulating the chip, the passive device, and the bonding wires.

- 11. The packaging structure of claim 10, wherein a portion of each first and second lead extends out of the encapsulant material.
 - 12. A quad flat package including the packaging structure of claim 10.
 - 13. A plastic chip carrier package including the packaging structure of claim 10.
- 14. The packaging structure of claim 10, wherein the passive device is a resistor, a capacitor or an inductor.

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a plurality of first leads defining a chip-bonding region in the leadframe structure; a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region;

an adhesive tape bonded to bottom surfaces of the contact pads; and a die pad arranged in the chip-bonding region.